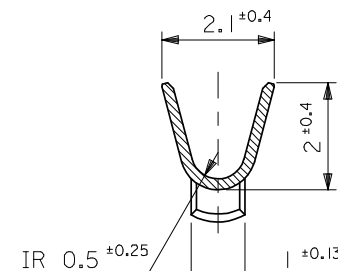
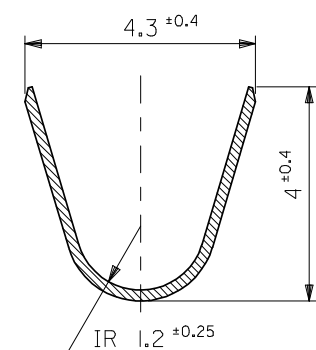


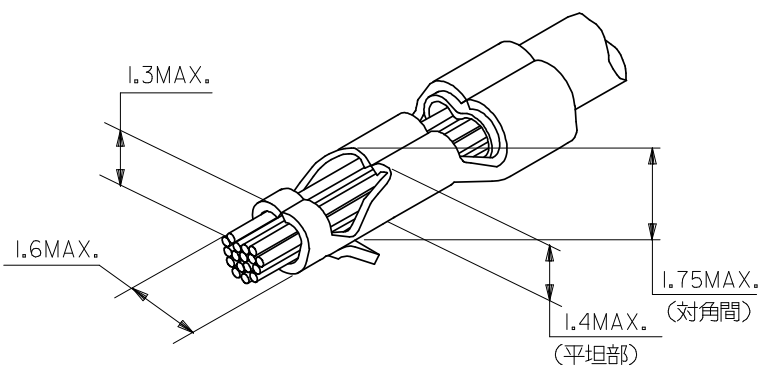
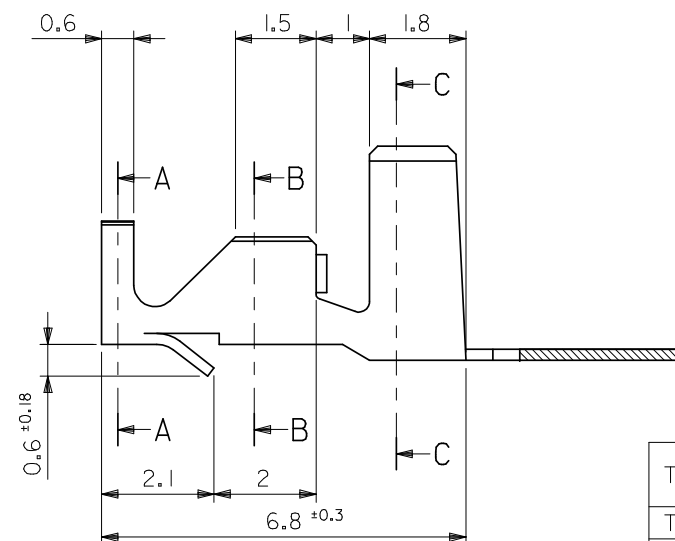
SECT. A-A



SECT. B-B



SECT. C-C



圧着外観図
OUTSIDE VIEW OF CRIMP

NOTES

- 推奨プリント基板穴径: $\phi 1.8^{+0.1}_0$
RECOMMENDED P.C.B. HOLES: $\phi 1.8^{+0.1}_0$
- 推奨プリント基板厚: $t1.57^{+0.2}$
RECOMMENDED P.C.B. THICKNESS: $1.57^{+0.2}$
- 材料の厚み: 0.203
MATERIAL THICKNESS: 0.203

TIN-LEAD(90-10) 3.8 μm MIN. OVER NICKEL 1.3 μm MIN.	PHOSPHOR BRONZE	CHAIN	39-00-0277	5298PBPT
	BRASS	CHAIN	39-00-0276	5298PT
TIN 0.9 μm MIN. REFLOW TREATMENT (PRE-PLATED)	PHOSPHOR BRONZE	CHAIN	39-00-0230	5298PBT
TIN 0.9 μm MIN. OVER COPPER 0.5 μm MIN. (PRE-PLATED)	BRASS	CHAIN	08-70-0106	5298T
PLATING	MATERIAL	FORM	EDP NO.	ENG. NO.

材料 MATERIAL	SEE TABLE & NOTE
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	AWG #18-22
被覆外径 INS. RANGE	$\phi 1.7-3.05$

REVISED EC NO: J2008-3347 DRAWN: NABEI CHKD: THARUYAMA APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)	10 UNDER	± 0.2
		10 OVER 30 UNDER	± 0.25
		30 OVER	± 0.3
		ANGULAR	$\pm 3^\circ$
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
H. HIRAMOTO	'91/09/05
CHECKED BY	DATE
H. HIRAMOTO	'93/07/06
APPROVED BY	DATE
M. FUKUSHIMA	'93/07/06
MATERIAL NO.	
SEE TABLE	
SIZE	A3

SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
LOW PROFILE PC BOARD CRIMP PIN		
MOLEX INCORPORATED		
DOCUMENT NO.	SD-5298-001	SHEET NO. 1 OF 1
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